



**Surface Mount Schottky Barrier Diode****Description**

- Low Forward Voltage
- High Current Capability
- Fast Switching Speed
- Surface Mount Device Type

Mechanical Data

- Case: SOT23 Package
 - Case Material: "Green" Molding Compound UL Flammability Classification Rating 94V-0
 - Terminals: Matte tin plated, solderable per MIL-STD-750, method 2026
 - Component in accordance to RoHS
 - Halogen Free
- Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

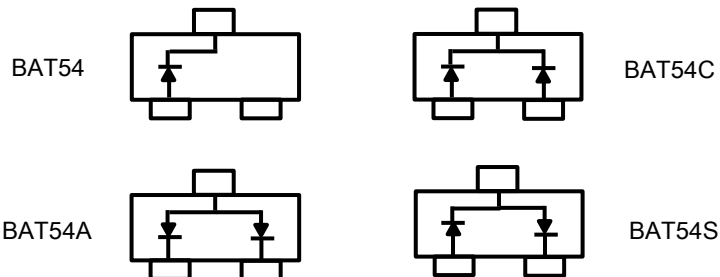
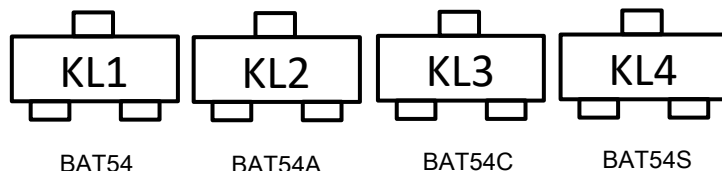
Ordering Information

- Package :SOT23
- Reel Size :7 (inches)
- Quantity Per Reel :3,000/Tape & Reel
- Quantity One Box :45,000/Tape & Reel

Forward Current - 0.2 A
Reverse Voltage - 30 V

Package Outline

SOT23 Top View

Device Schematic & PIN Configuration**Product Type Marking Code****Maximum Ratings (@TA = +25°C, unless otherwise specified.)****Absolute Ratings**

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	30	V
Forward Rectified Current	I_{FM}	200	mA
Repetitive Peak Forward Current @ $t \leq 1s, \delta \leq 0.5$	I_{FRM}	300	mA
Peak Forward Surge Current @ $t = 8.3ms$	I_{FSM}	600	mA
Power Dissipation	P_D	200	mW
Storage Temperature Range	T_{STG}	-55 to +150	°C
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	500	°C/W
Junction Temperature	T_J	125	°C

Electrical Characteristics

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Reverse Voltage	$I_R = 100\mu A$	V_{BR}	30	—	—	V
Reverse Current	$V_R = 25V$	I_R	—	—	2	μA
Forward Voltage	$I_F = 0.1mA$	V_F	—	—	0.24	V
	$I_F = 1mA$		—	—	0.32	
	$I_F = 10mA$		—	—	0.40	
	$I_F = 30mA$		—	—	0.50	
	$I_F = 100mA$		—	—	1.00	
Junction Capacitance	$V_R = 1V, F = 1MHz$	C_J	—	—	10	pF
Reverse Recovery time	$I_F = I_R = 10mA$ $I_{RR} = 0.1 \times I_R, RL = 100\Omega$	T_{RR}	—	—	5	ns



Rating and Characteristic Curves

FIG.1 - Forward Characteristics

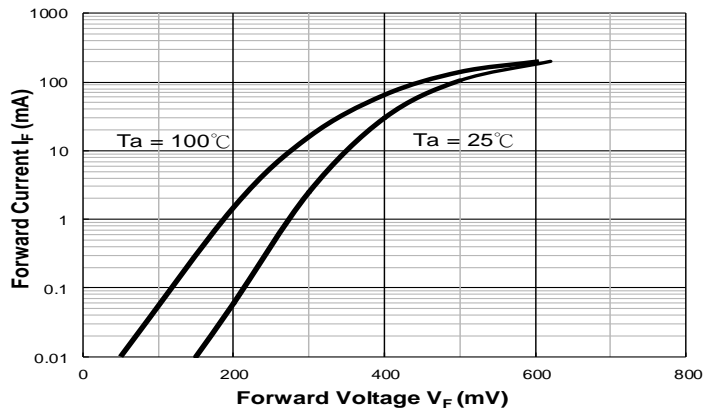


FIG.2 - Reverse Characteristics

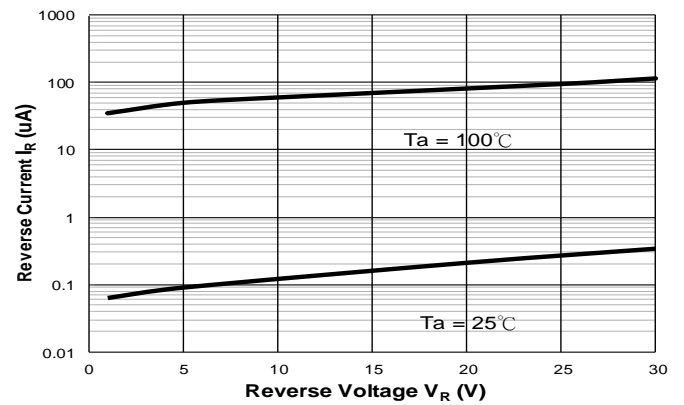


FIG.3 - Power Derating Curve

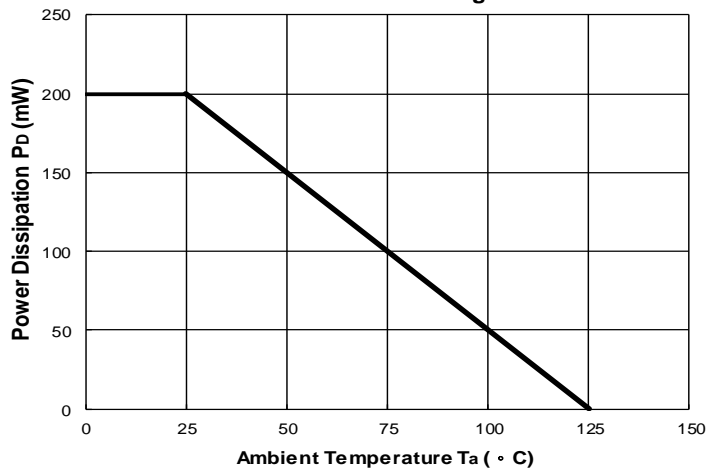
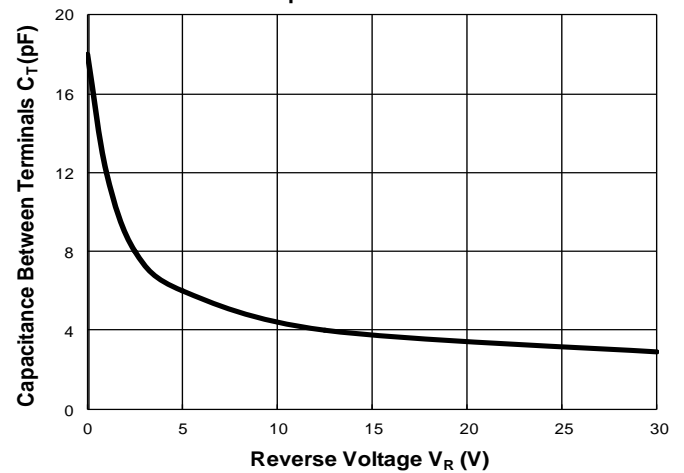
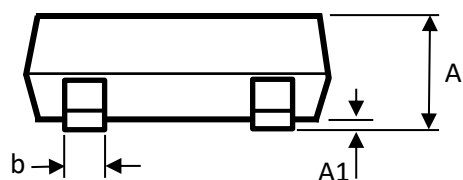
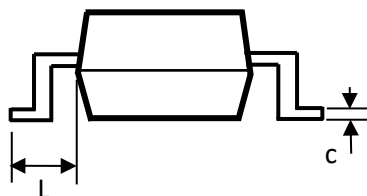
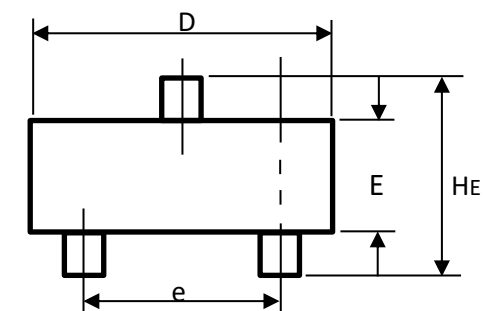


FIG.4 - Capacitance Characteristics



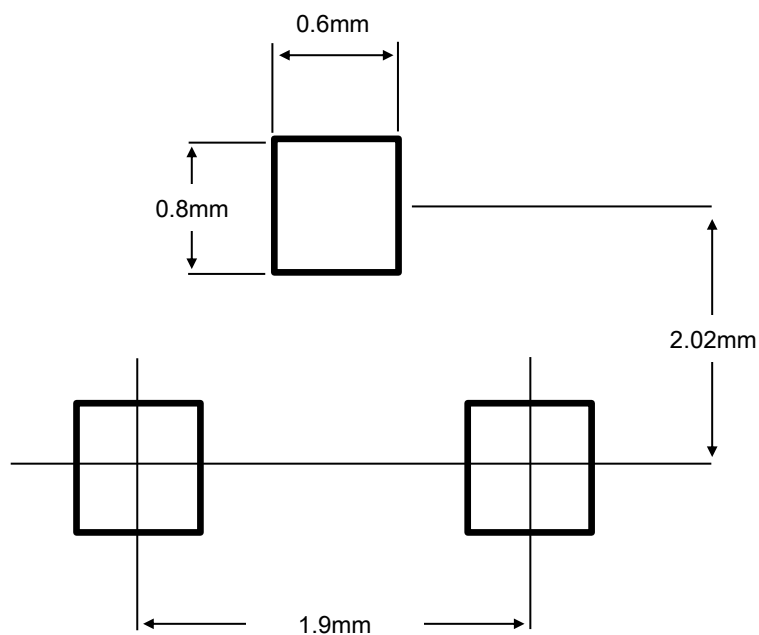


Package Outline Dimensions



SOT23 Package		
Dim	Min	Max
A	0.90	1.15
A1	0.00	0.10
b	0.30	0.50
c	0.08	0.15
D	2.80	3.00
E	1.20	1.40
e	1.80	2.00
L	0.55 REF	
HE	2.25	2.55
All Dimensions in mm		

Suggested Soldering Pad Layout



Note:

- 1.The pad layout is for reference purposes only.
- 2.General tolerance $\pm 0.05\text{mm}$



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